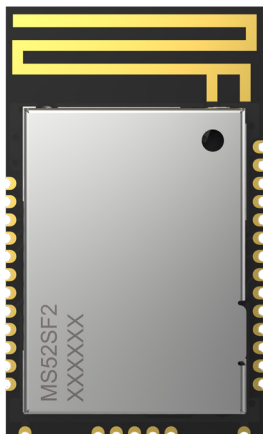


# Bluetooth LE Module

## MS52SF2



Datasheet  
V 1.1.1



# Version Note

Version	Details	Contributor(s)	Date	Notes
1.0.0	First edit	Michelle, Leo	2024.05.13	
1.1.1	Added static protection recommendations	Michelle, Leo	2024.06.28	

# Part Number

Model	Hardware Code
MS52SF21	1N08AI

Click the icon to view and download the latest product documents electronically.  
[https://en.minewsemi.com/file/MS52SF2-TLSR8208\\_Datasheet\\_C\\_EN.pdf](https://en.minewsemi.com/file/MS52SF2-TLSR8208_Datasheet_C_EN.pdf)



# MS52SF2-TLSR8208

## Bluetooth transparent slave module that supports serial port instruction configuration and iBeacon broadcast mode

MS52SF2 is a module with Bluetooth slave device firmware designed using Tailing Micro TLSR8208 chip. It has broadcast and connection status, and uses UART interface to transparently transmit data between main devices such as mobile phones/tablets and MCU. Bluetooth functionality can be added to the product without the need for Bluetooth development, providing convenience for product development. The device broadcast communicates with the MCU through the UART interface. In broadcast mode, the MCU can set and view the module's broadcast name in command format, set custom data, modify parameters such as broadcast interval and connection interval through the UART interface. When a host connects to a device through Bluetooth, the device will act as a bridge between the host and the MCU for transparent data transmission.

### FEATURES



Transmission rates up to 5kB/s



Support serial port instruction configuration



Support iBeacon broadcast mode

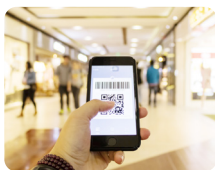
### KEY PARAMETER

MS52SF2-TLSR8208			
Chip Model	Telink TLSR8208	Antenna	PCB
Module Size	20×12×2mm	GPIO	15
Flash	128kB	RAM	16KB
Receiver sensitivity	-97dBm	Transmitting power	-45~ +10dBm
Current(TX)	0dBm-9.5mA	Current(RX)	9.1mA
Firmware	Transparent Slave Firmware		

### APPLICATION



Smart Home



Consumer Electronics



Intelligent Medical care



Security Equipment



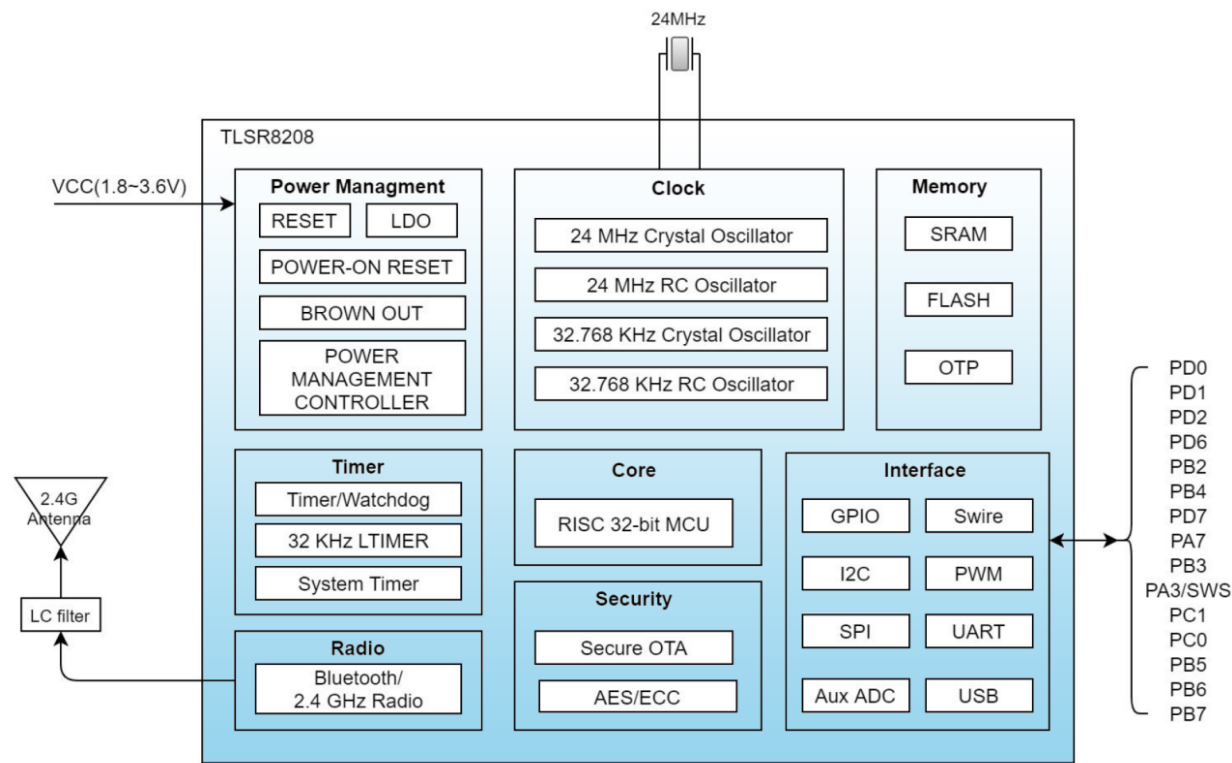
Automotive equipment



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1 BLOCK DIAGRAM



2 ELECTRICAL SPECIFICATION

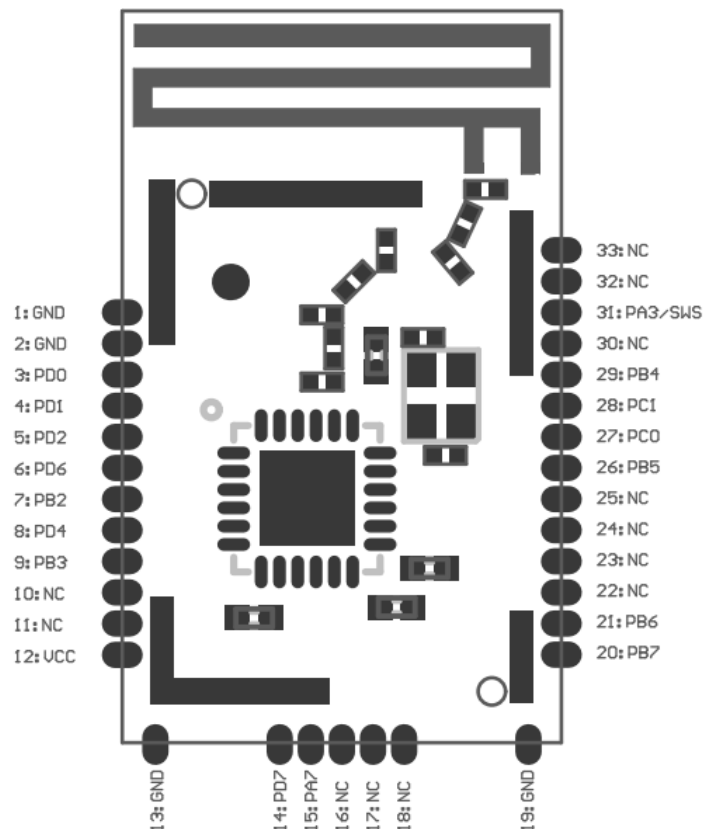
Parameters	Value	Notes
Working Voltage	1.8V-3.6V	To ensure RF work, supply voltage suggest not lower than 2.5V
Working Temperature	-40℃~+85℃	Storage temperature is -40℃~+105℃
Transmission Power	-45 ~ +10dBm	Configurable
Receiving Current	9.1mA	RF reception current in 1Mbps mode
Emission Current	9.5mA	RF emission current in 0dB mode
Module Dimension	20*12*2mm	
Quantity of IO Port	15	

### 3 CURRENT CONSUMPTION CHARACTERISTICS

The following power consumption test is conducted at room temperature with a power supply voltage of 3.3V. The broadcast interval is 1s, and the maximum and minimum connection interval is 20-40ms. The calculation of service life is generally based on the average power consumption (Avg).

Status	Consumption	Peak(mA)	Avg(mA)
	Average current in sleep state (SLP and BTDATA pulled high)	0.0018	0.00067
	Broadcast average current (SLP pin to GND)	12.29	0.0435
	Connection state average current (SLP pin is connected to GND, BTDATA is pulled high)	13.14	0.295
	Transparent transmission average current (SLP, BTDATA pins are connected to GND, connected to mobile phones)	13.22	3.59

### 4 PIN DESCRIPTION



## 5 PIN DEFINITION

Pin Number	Symbol	Type	Definition	Notes
1-2	GND	GND	Ground	
3~9	PD0 to PB3		GPIO	Not used in UART, floating
10~11	NC			
12	VCC	VCC	Power Supply	
13	GND	GND	Ground	
14	PD7	BTX	UART TX	TX of Bluetooth Module
15	PA7	BRX	UART RX	RX of Bluetooth Module
16~18	NC			
19	GVD	GND	Ground	
20	PB7	CON_IND	Connection indication	Sleep state: low level Broadcast status: Low level Connection status: High level
21	PB6		GPIO	
22~25	NC			
26	PB5	SLP		Low level to wake-up, high level to sleep, no floating
27	PC0	BTDATA	Sleep/Awake Serial port control	Serial port on / off to control pin, no floating 0: serial port open, can send and receive serial port data 1: Serial port off
28~29	PC1-PB4		GPIO	Not used in UART, floating
30	NC			
31	PA3~SWS		Burn pin	Used for burning firmware
32~33	NC			



## 6 MODULE OPERATION INSTRUCTION

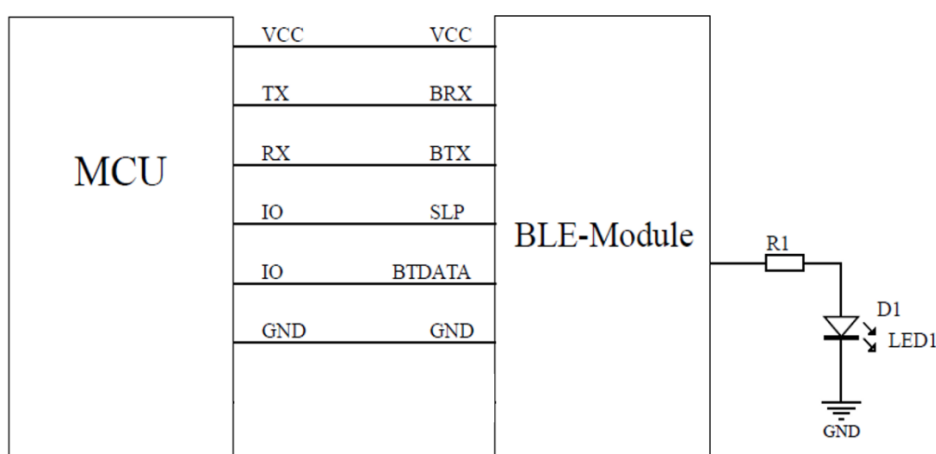
### 6.1 Tool

Mobile app: Minew serial port assistant, nRF connect (also known as nRF Master Control Panel). When testing BLE products, it is not possible to use the built-in Bluetooth directly when using the system settings, especially on the IOS end. The Bluetooth settings inside will not display BLE devices.

Download the IOS directly from the APP store.

PC serial port assistant: Baidu "Friendly Serial Port Assistant" can be downloaded. The PC serial port assistant is used to debug the UART interface of the module.

### 6.2 Demonstration of module application



#### 6.2.1 Power supply

The SoC working voltage is 1.7V-3.6V, to ensure a stable function, supply voltage should be 3.0V-3.6V.

#### 6.2.2 SLP(Sleep/Awake)

When pull SLP low, the module in broadcast mode. BLE device can be found by smartphone APP, Device name: Minew\_Vxxxxx(default) name, module can be connected with smartphone and enters connection mode. When pull SLP high, device will enter sleep mode.



Note: This pin cannot be left floating to avoid unpredictable errors.

#### 6.2.3 BTDATA(UART control)

The BTDATA pin is only valid when SLP is low. SLP is low, BTDATA is low, and when the module is in a broadcast state, all UART data will be considered as instructions. When the module is connected, all data is considered transparent.



Note: This pin cannot be left floating to avoid unpredictable errors.





## 6.2.4 UART interface:TX and RX

When both SLP and BTDATA in low level,UART port will be activated,the module TX and RX should be connected to MCU RX and TX,then start to communicate through UART.

In the test,module TX and RX can be connected with an UART to USB module's RX and TX pin, then send command through Serial Port Utility App from PC.



Note: The TX and RX of 2 modules can be connected reversed, each module connect with a smart phone, then transfer data over BLE between each smart phone.

## 6.2.5 CON\_IND

CON\_IND is used to indicate module status,high level in connection mode, low level in sleep or broadcast mode to wake up MCU and save power.

## 6.2.6 FIFO\_FULL

FIFO\_FULL is used to indicate whether the cache is full or not. When sending large amount of data from MCU to module, this pin can be added to judge. If it is high, then the FIFO is full, and you can not continue to send UART data at this time to avoid packet loss.

## 6.2.7 Command instruction

After connecting VCC and GND, the SLP and BTDATA pins are directly grounded. At this time, the module is in an unconnected state, that is, the module is in command mode and the serial port is turned on. Instructions can be sent to set and query parameters.

For all device instructions, the returning result is the same:

54544D3A4F4B0D0A00(TTM:OK\r\n\0) is returned after command sent successfully

54544D3A4552500D0A00 (TTM:ERP\r\n\0) is returned after command failed

After sending the correct setting command, the parameters take effect immediately (the baud rate only takes effect after sending the reset command), and the power outage will not be saved at this time. Only after sending the reset command will it be saved to flash.

Below is the list of setup instructions:



Note: The first line in the command list should be sent by Hex format, the second line should be sent by ASCII format. When checking the parameter, the returned result are all hexadecimal numbers, so you need to use hexadecimal numbers to parse the command.phone.



Function	Command (hex/ASCII)	Description
Setting the broadcast name	54544D3A52454E2D<Para> TTM:REN-<Para>	Length: 1-16 Byte, Value: ASCII
Setting the broadcast interval	54544D3A4144502D <Para> TTM:ADP-<Para>	Length: 1 Byte, value: 1-20, corresponding to broadcast interval 1*100ms.
Setting the Connection Interval	54544D3A4349542D<Para> TTM:CIT-<Para>	Length: 1 Byte, <Para> can only be represented in hexadecimal as 0x01~0x64; The actual connection interval is (<Para>*10~<Para>*10+20)ms
Setting the baud rate	54544D3A4250532D<Para> TTM:BPS-<Para>	Length: 1 Byte, values: 0-4, corresponding to 9600/19200/38400/57600/115200 (unit: bps)
Setting the transmit power	54544D3A54504C2D <Para> TTM:TPL-<Para>	Length: 1 Byte, Values: 0-8, corresponding to -40, -20, -16, -12, -8, -4, 0, +4, +8 (unit: dB)
Setting the broadcast data	54544D3A4144442D <Para> TTM:ADD-<Para>	Length: 1-16 Byte, value: any hexadecimal number
Setting the factory ID	54544D3A5049442D <Para> TTM:PID-<Para>	Length: 2 Byte, value: any hexadecimal number
Setting the Service UUID	54544D3A5549442D <Para> TTM:UID-<Para>	Length: 6Byte, (2 Byte service uuid+2 Byte rx UUID+2 Byte tx UUID) Values: Any hexadecimal number, service, rx, tx UUID can't be the same.
Setting the broadcast mode	54544D3A4D4F442D <Para> TTM:MOD-<Para>	Set device broadcast packet format: 0: pass-through broadcast packet 1: iBeacon broadcast packet, you can see the specific broadcast packet format instructions
Setting the UUID of iBeacon	54544D3A4149442D <Para> TTM:AID-<Para>	Length: 16 bytes, value: any hexadecimal number
Set Major	54544D3A4D414A2D<Para> TTM:MAJ-<Para>	Length: 2 bytes, value: any hexadecimal number
Set Minor	54544D3A4D494E2D <Para> TTM:MIN-<Para>	Length: 2 bytes, value: any hexadecimal number
Setting the connection mode	54544D3A5057452D <Para> TTM:PWE-<Para>	Whether the device requires a password to connect, 0: no password required to connect 1: Connection password required
Setting the connection password	54544D3A5057442D <Para> TTM:PWD-<Para>	Length: 1-8 bytes, value: ASCII, the correct password must be entered within 5s on the connection, otherwise the connection will be disconnected

Function	Command (hex/ASCII)	Description
Restore factory equipment	54544D3A5253542D464143 TTM:RST-FAC	Consistent with setting instruction return
Reset	54544D3A525342D535953 TTM:RST-SYS	Modify the confirmation command, the command is correct and there is no return

To ensure successful parameter setting, a parameter reading instruction has been added, which reads the current effective parameters of the device. When the instruction is incorrect, it returns 54544D3A455250D0A00(TTM:ERP\r\n0)

Function	Command (hex/ASCII)	Description
Read broadcast name	54544D3A52454E3F TTM:REN?	Return TTM: REN xxx r\ n \0, return parameter is ASCII
Read broadcast interval	54544D3A4144503F TTM:ADP?	Return TTM: ADP-xxx r\ n \0, return parameter is hexadecimal
Read Connection Interval	54544D3A4349543F TTM:CIT?	Return TTM: CIT-xxx r\ n \0, return parameter is hexadecimal
Read Baud Rate	54544D3A4250533F TTM:BPS?	Return TTM: BPS-xxx r\ n \0, return parameter is hexadecimal
Read transmit power	54544D3A54504C3F TTM:TPL?	Return TTM: TPL-xxx r\ n \0, return parameter is hexadecimal
Read broadcast data	54544D3A4144443F TTM:ADD?	Return TTM: ADD-xxx r\ n \0, return parameter is hexadecimal
Read factory ID	54544D3A5049443F TTM:PID?	Return TTM: PID-xxx r\ n \0, return parameter is hexadecimal
Read Service UUID	54544D3A5549443F TTM:UID?	Return TTM: UID-xxx r\ n \0, return parameter is hexadecimal
Read broadcast mode	54544D3A4D4F443F TTM:MOD?	Return TTM: MOD-xxx r\ n \0, return parameter is hexadecimal
Read UUID	54544D3A4149443F TTM:AID?	Return TTM: AID-xxx r\ n \0, return parameter is hexadecimal

Function	Command (hex/ASCII)	Description
Read Major	54544D3A4D414A3F TTM:MAJ?	Return TTM: MAJ-xxx r\n \0, return parameter is hexadecimal
Reading the Minor of iBeacon	54544D3A4D494E3F TTM:MIN?	Return TTM:MIN-xxx r\n \0, return parameter is hexadecimal
Read Connection Mode	54544D3A5057453F TTM:PWE?	Return TTM: PWE-xxx r\n \0, return parameter is hexadecimal
Read Connection Password	54544D3A5057443F TTM:PWD?	Return TTM: PWD-xxx r\n \0, return parameter is ASCII
Read MAC address	54544D3A4D4143(2D)3F TTM:MAC-? or TTM:MAC?	Return TTM: MAC-xxx r\n \0, return parameter is hexadecimal
Read version information	54544D3A564552(2D)3F TTM:VER-? or TTM:VER?	Return TTM: VER xxx r\n \0, return parameter is ASCII

## 6.3 Example of operation

### 6.3.1 Factory Default Parameters

Broadcast Name: Minew\_Vxxxxx  
 Serial port baud rate: 9600bps,8N1  
 Transmit power: 0dBm  
 Broadcast interval: 1s  
 Broadcast mode: transparent broadcast package  
 Custom data: Minew Tech  
 Minimum and maximum connection interval: 20ms - 40ms  
 Connection password enable: not enabled  
 Connection password: minew123  
 Major: 0x1234  
 minor: 0x1235  
 UUID: 74278BDA-B644-4520-8F0C-720EAF059935

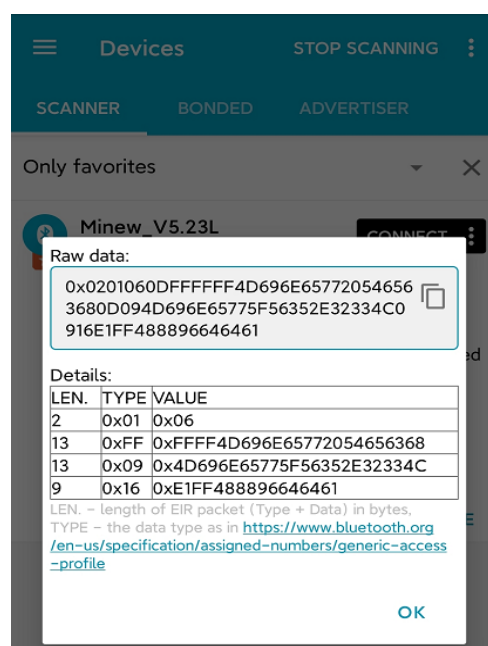
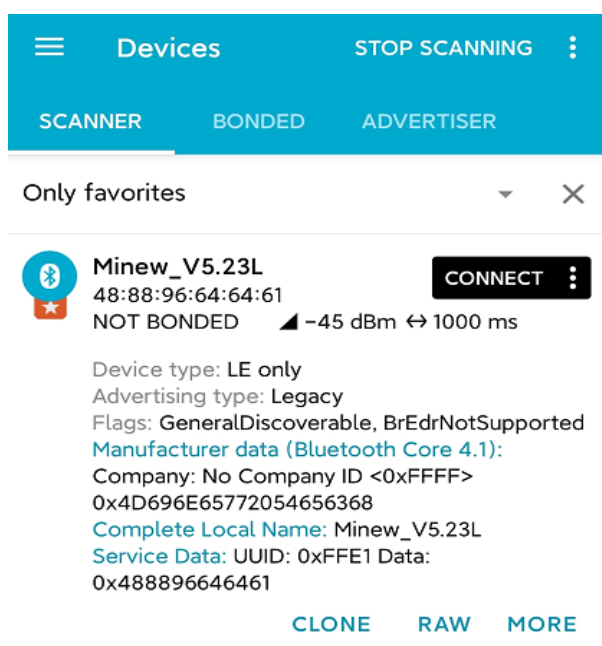


## 6.3.2 Broadcast packet (broadcast packet+reply packet)

Use nrf connect to scan the device, click Raw after scanning to the device, Raw data is the unparsed data of the scanned device. After parsing the data according to BLE data type, see Detail section, BLE broadcast data has a certain format: length + type + content.

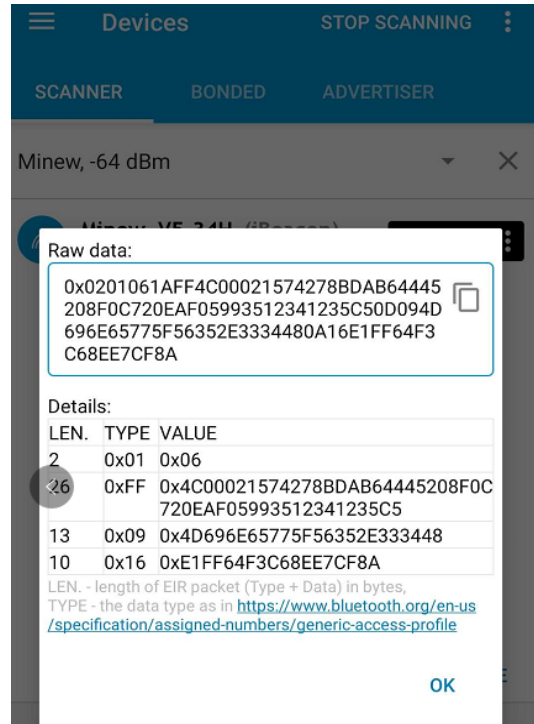
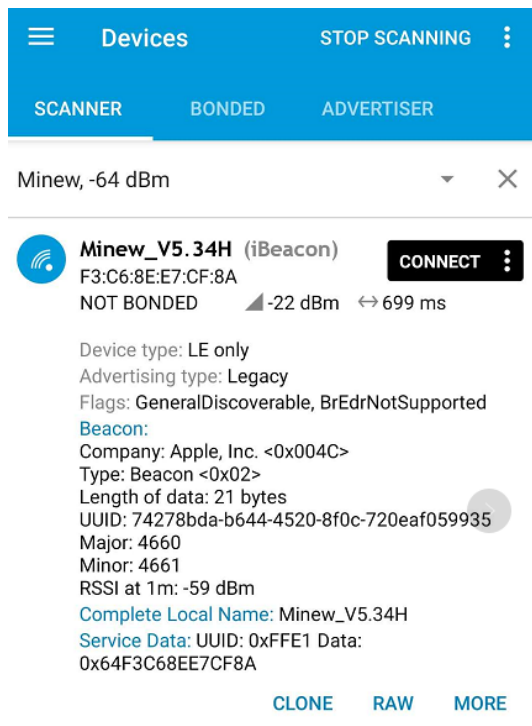
The content is changeable, the type is fixed and the length is determined by the content. There are two broadcast formats for the device, the pass-through broadcast packet and the iBeacon broadcast packet. Both formats contain four types: flag(0x01), broadcast name(0x09), service data(0x16), and manufacturer data(0xFF).

The following figure shows the transmitting broadcast packet: flag, broadcast name, service data is put in the broadcast packet, manufacturer data is put in the reply packet. The service data content is: service data UUID(E1FF) + MAC address. manufacturer data content consists of company id(3906) + battery level information(1 byte) + custom data.



Note: The IOS side can not get the content of the MAC address field, so the MAC address is put back into the broadcast packet to ensure that the IOS side can get the device MAC address. In addition, the WeChat applet can't get the reply packet, so the MAC is put into the service data of the broadcast packet to ensure that the IOS side can also get the device MAC address using the WeChat applet connection.

The following figure shows the iBeacon broadcast packet: flag, manufacturer data is put in the broadcast packet, service data and broadcast name are put in the reply packet. The broadcast packet must follow this fixed format to fulfill the iBeacon protocol definition. In manufacturer data data, 4C 00 is Apple's company id, 02 15 is iBeacon's fixed format, Proximity uuid(16 bytes)+Major(2 bytes)+Minor(2 bytes)+Measured power(1 byte). In iBeacon broadcast mode, manufacturer data can only change the value of Proximity uuid, Major, Minor.  
service data= service data UUID(FFE1) + battery level information + MAC address.

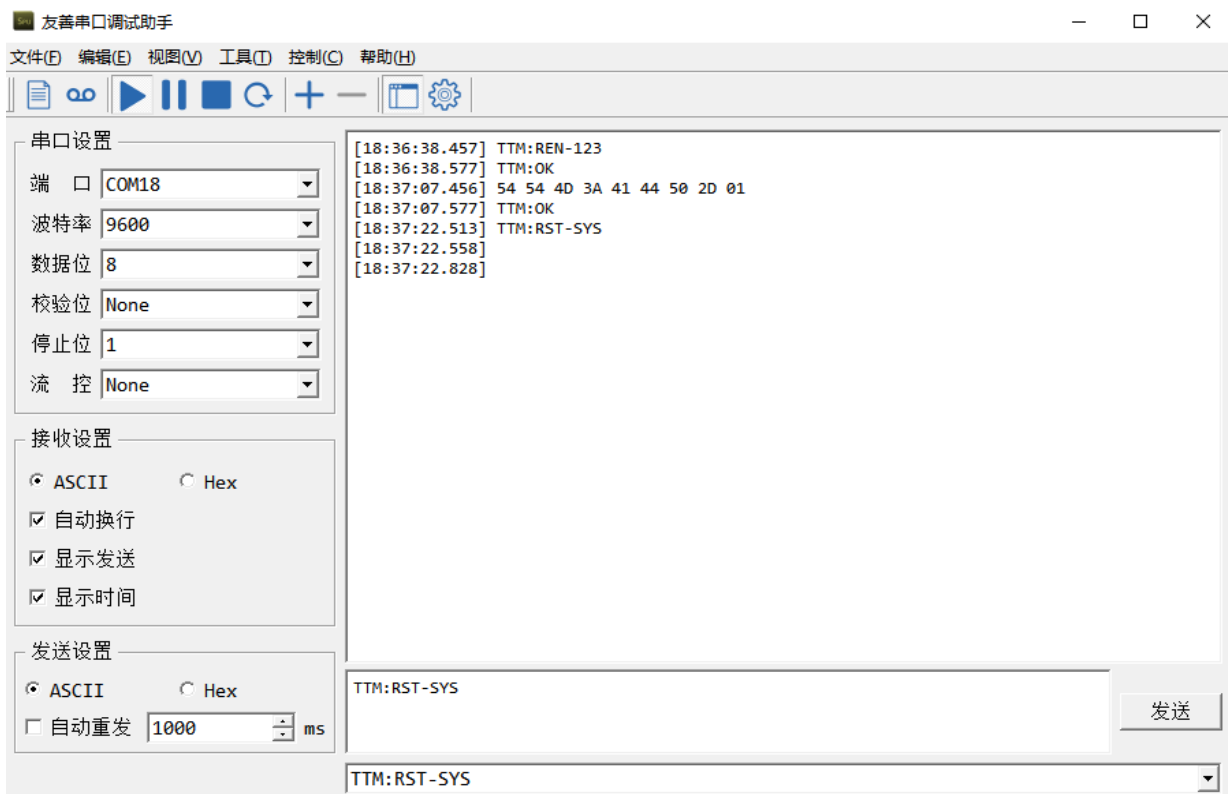


### 6.3.3 Example of Modifying Parameters

Connect all pins according to the wiring method, with SLP and BTDATA grounded. At this time, the broadcast name can be viewed through the mobile app (Minew serial assistant or nRF connect) as Minew\_Vxxxxx device. In this state, if the serial port sends TTM: REN-123, it will return TTM: OK r n 0. The parameters will not take effect until the reset command is sent, and power down saving will be achieved.



Note: When multiple parameters need to be modified, all setting commands can be sent first, and then reset commands can be sent.



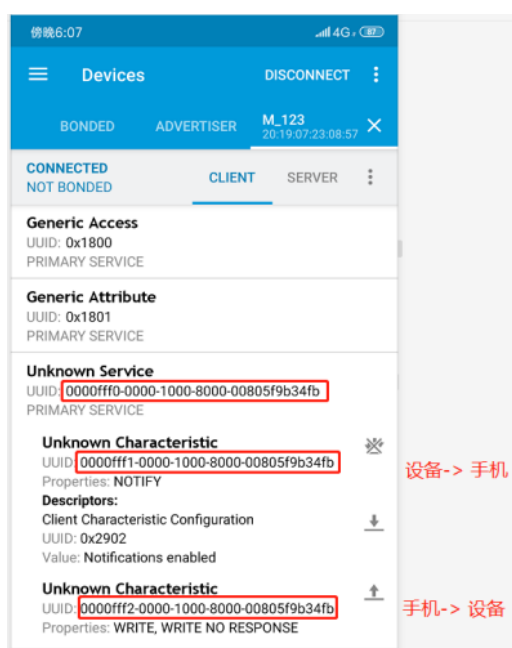
When querying device parameters, due to the fact that the parameters are hexadecimal numbers, when selecting ASCII display, the parameter position may be garbled. In this case, it is necessary to set it to HEX display. The parameters correspond to the position after 2D, as shown in the above figure. To query the baud rate, it is necessary to use HEX display to view the specific parameters.

### 6.3.4 Transparent transmission

Based on 7.3, connect to the device using the mobile app and keep the BTDATA pin low to perform data passthrough. when BTDATA is not low, it does not affect the broadcasting and connecting of the device, just that passthrough is not possible. Using nRF connect, you can see the specific service, characteristic and corresponding properties.

The UUID consists of the alias UUID (2 byte, 3.4 byte on the left in the figure) + the base UUID (the remaining 14 byte).

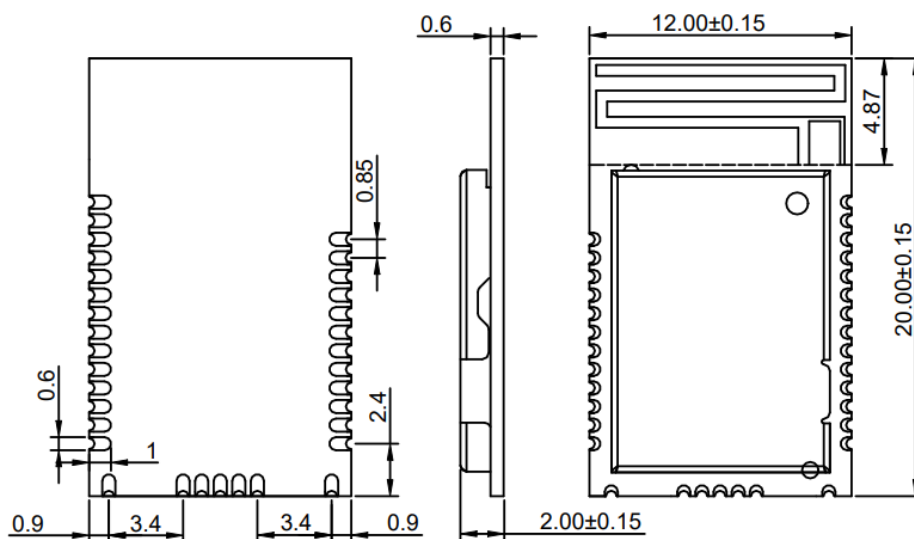
The base UUID used for services, features in the passthrough program is standard and is illustrated below with the alias UUID.



FFF0 is the service UUID, FFF1 is the cell phone receives data and the module sends data; FFF2 is the cell phone sends data and the module receives data.

Eigenvalue UUID	Executable operation	Maximum Packet Length	Note
FFF1	notify	244	The serial port sends data to the module and forwards it to the phone. Data can only be obtained after the phone is enabled to notify. The maximum number of bytes emitted by a module packet is 244 bytes
FFF2	write	244	The phone sends data to the module and forwards it to the serial port. When using the API interface function to write data, the maximum length of data written at one time is 244 bytes

## 7 MECHANICAL DRAWING

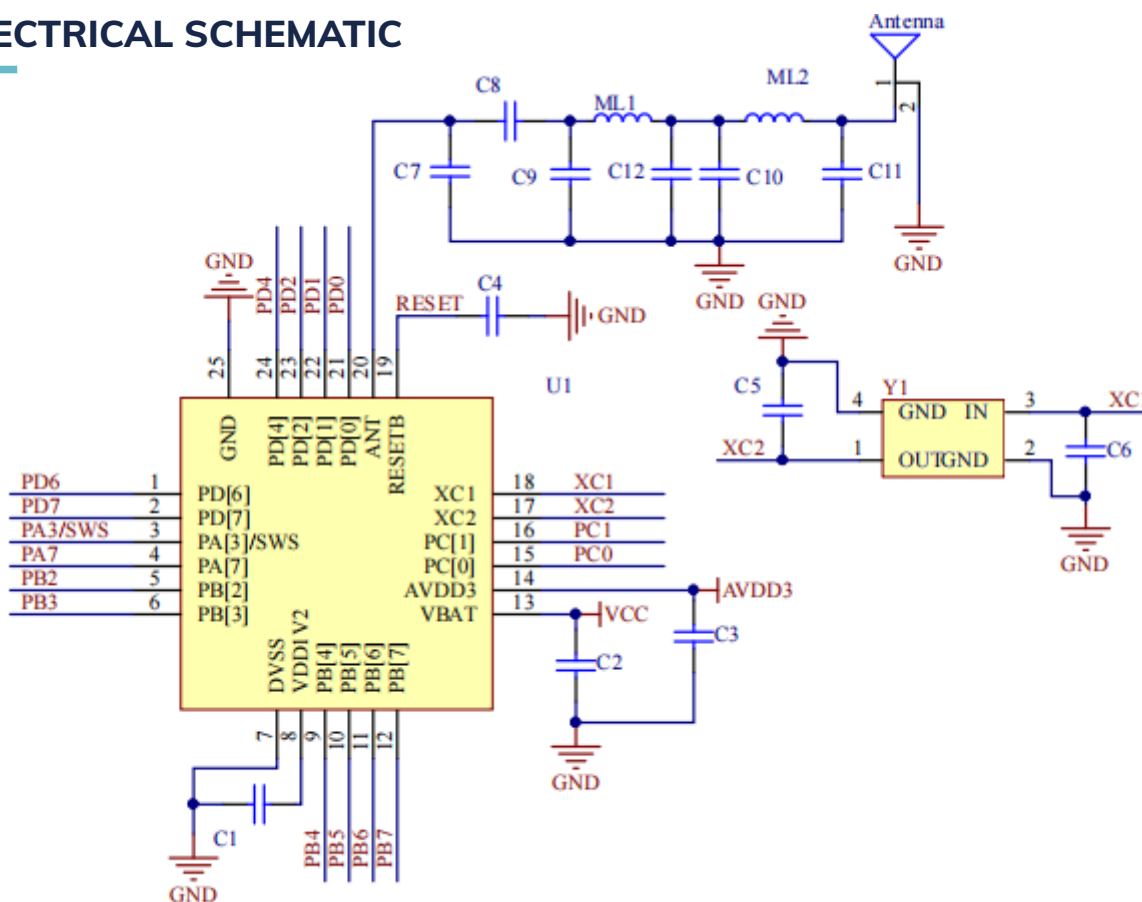


Default unit: mm Default tolerance: ±0.15



Note: Recommended pad size 1.8\*0.8mm, pad extends outward 0.5mm

## 8 ELECTRICAL SCHEMATIC



Notice: Before placing an order, please confirm the specific configuration required with the salesperson.





## 9 PCB LAYOUT

There should be no GND plane or metal cross wiring in the module antenna area, and components should not be placed nearby. It is best to make a hollow or clear area, or place it on the edge of the PCB board.



Notice: Refer to examples as below, and highly suggest to use the first design and the adjustment of modules antenna design according to the first wiring.

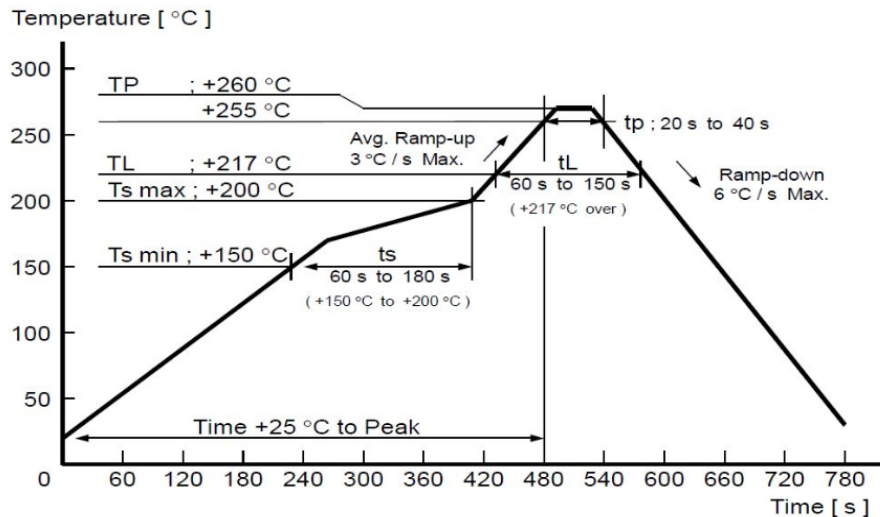
### Layout Notes:

- 1) Preferred Module antenna area completely clearance and not be prevented by metals, otherwise it will influence antenna's effect (as above DWG. indication).
- 2) Cover the external part of module antenna area with copper as far as possible to reduce the main board's signal cable and other disturbing.
- 3) It is preferred to have a clearance area of 4 square meter or more area around the module antenna (including the shell) to reduce the influence to antenna.
- 4) Device should be grounded well to reduce the parasitic inductance.
- 5) Do not cover copper under module's antenna in order to avoid affect signal radiation or lead to transmission distance affected.
- 6) Antenna should keep far from other circuits to prevent radiation efficiency reduction or affects the normal operation of other lines.
- 7) Module should be placed on edge of circuit board and keep a distance away from other circuits.
- 8) Suggesting to use magnetic beads to insulate module's access power supply.



## 10 REFLOW AND SOLDERING

- 1) Do SMT according to above reflow oven temperature deal curve. Max. Temperature is 260℃; Refer to IPC/JEDEC standard; Peak TEMP<260℃; Times: ≤2 times, suggest only do once reflow soldering on module surface in case of SMT double pad involved. Contact us if special crafts involved.
- 2) Suggesting to make 0.2mm thickness of module SMT for partial ladder steel mesh, then make the opening extend 0.8mm
- 3) After unsealing, it cannot be used up at one time, should be vacuumed for storage, couldn't be exposed in the air for long time. Please avoid getting damp and soldering-pan oxidizing. If there are 7 to 30 days interval before using online SMT, suggest to bake at 65-70℃ for 24 hours without disassembling the tape.
- 4) Before using SMT, please adopt ESD protection measure.



## 10.1 ESD Static Protection Recommendations

Categorization	Step	Note
Personnel related	<ol style="list-style-type: none"> <li>1、 Anti-static ring (grounding)</li> <li>2、 Anti-static clothing</li> <li>3、 Anti-static gloves</li> <li>4、 Anti-static hat</li> <li>5、 Anti-static chair grounding</li> <li>6、 Anti-static shoes</li> <li>7、 Anti-static flooring</li> </ol>	<p>All need to use anti-static material</p> <p>1.Anti-static material: resistance 10<sup>4</sup>~10<sup>11</sup>Ω 2.Insulator: resistance&gt;10<sup>11</sup>Ω</p>
Machines, equipment, tables, trolleys, lockers	<ol style="list-style-type: none"> <li>1. Use anti-static materials for parts in contact with products (e.g. anti-static tablecloths, anti-static table mats)</li> <li>2. Grounding of machines, equipment, tables, trolleys and lockers</li> </ol>	<p>Grounding instructions are as follows:</p> <ol style="list-style-type: none"> <li>1. Auxiliary grounding wire (earth), resistance value &lt;25Ω</li> <li>2. Discreet: ground of the distribution box, resistance value &lt;1Ω</li> </ol>
Environments	<ol style="list-style-type: none"> <li>1. Workshop humidity control 40%~60%, temperature 20°C~30°C;</li> <li>2. Ion fan dissipation;</li> </ol>	<p>Ion blower:</p> <ol style="list-style-type: none"> <li>1. Confirm whether the point check is effective;</li> <li>2. Installation in the workstation that is easy to generate static electricity, such as: testing, assembly and other links.</li> </ol>

The statistics show that:

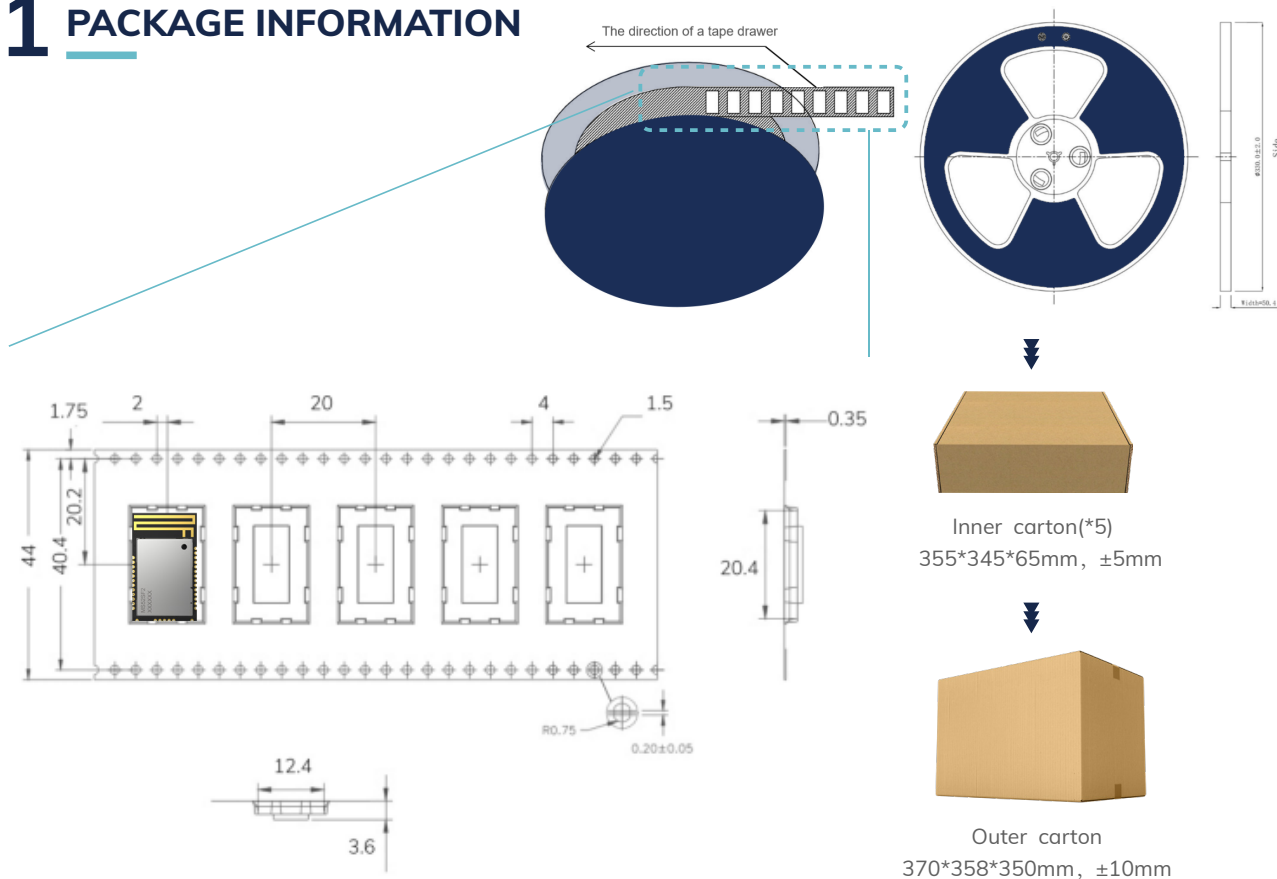
In the Action mode, which has been well protected against ESD, ESD electrostatic damage still occurs in the module: HBM mode (external discharge to the chip), accounting for about 20%

CDM mode (the chip is connected to the external discharge), accounting for about 80%.

Note: The ESD test condition of module chip HBM (JESD22A-114 reference standard) only reaches +/-2KV standard level, and CDM (JESD22-C101 reference standard) only reaches +/-500V standard level, so please do the corresponding ESD protection measures.

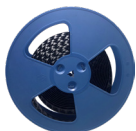


# 11 PACKAGE INFORMATION

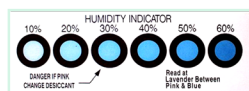


## Remarks

General material list for FCL packaging:



Carrier tape packaging tray



Humidity Indicator  
(1 pcs/bag)



Desiccant  
(placed in a vacuum bag)



Vacuum bag



Inner carton(\*5)  
355\*345\*65mm, ±5mm



Outer carton  
370\*358\*350mm, ±10mm

## Other:

Moisture-proof label (attached to the vacuum bag)

Certification label (attached to the vacuum bag)

Outer box label



Default unit: mm Default tolerance: ±0.1

Packing detail	Specification	Net weight	Gross weight	Dimension
MS52SF2	850PCS	425g	1290g	W=44mm, T=0.35mm



Note: Default weight tolerance all are within 10g (except the special notes)

## 12 STORAGE CONDITIONS

- Please use this product within 6 months after signing the receipt.
  - This product should be stored without opening the package at an ambient temperature of 5~35°C and a humidity of 20~70%RH.
  - This product should be left for more than 6 months after receipt and should be confirmed before use.
  - The product must be stored in a non-corrosive gas (Cl<sub>2</sub>, NH<sub>3</sub>, SO<sub>2</sub>, NO<sub>x</sub>, etc.).
  - To avoid damaging the packaging material, do not apply any excessive mechanical shocks, including but not limited to sharp objects adhering to the packaging material and product dropping.
- This product is suitable for MSL2 (based on JEDEC standard J-STD-020).
  - After opening the package, the product must be stored at ≤30°C/<60%RH. It is recommended to use the product within 3-6 months after opening the package.
  - When the color of the indicator in the package changes, the product should be baked before welding.
- Baking is not required for one year if exposure is limited to <30°C and 60%RH. Refer to MSL2 for exposure criteria for moisture sensitivity level. If exposed to (≥168h@85°C/60%RH) conditions or stored for more than one year, recommended baking conditions.
  1. 120 ±5/-5°C, 8 hours, 1 timeProducts must be baked individually on heat-resistant trays because the materials (base tape, reel tape, and cover tape) are not heat-resistant, and the packaging material may be deformed at temperatures of 120°C;
  2. 90°C ±8/-0°C, 24hours, 1timesThe base tape can be baked together with the product at this temperature. Please pay attention to the uniformity of heat.

## 13 HANDLING CONDITIONS

- Be careful in handling or transporting products because excessive stress or mechanical shock may break products.
- Handle with care if products may have cracks or damages on their terminals. If there is any such damage, the characteristics of products may change. Do not touch products with bare hands that may result in poor solder ability and destroy by static electrical charge.

## 14 QUALITY

Cognizant of our commitment to quality, we operate our own factory equipped with state-of-the-art production facilities and a meticulous quality management system. We hold certifications for ISO9001, ISO14001, ISO27001, OHSAS18001, BSCI.

Every product undergoes stringent testing, including transmit power, sensitivity, power consumption, stability, and aging tests. Our fully automated module production line is now in full operation, boasting a production capacity in the millions, capable of meeting high-volume production demands.

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## 16 RELATED DOCUMENTS

- Telink TLSR8208\_Chip\_Datasheet  
[https://en.minewsemi.com/file/Telink\\_TLSR8208\\_Chip\\_Datasheet\\_EN.pdf](https://en.minewsemi.com/file/Telink_TLSR8208_Chip_Datasheet_EN.pdf)
- MinewSemi\_Product\_Naming\_Reference\_Manual\_V1.0  
[https://en.minewsemi.com/file/MinewSemi\\_Product\\_Naming\\_Reference\\_Manual\\_EN.pdf](https://en.minewsemi.com/file/MinewSemi_Product_Naming_Reference_Manual_EN.pdf)
- MinewSemi\_Connectivity\_Module\_Catalogue\_V2.0  
[https://en.minewsemi.com/file/MinewSemi\\_Connectivity\\_Module\\_Catalogue\\_EN.pdf](https://en.minewsemi.com/file/MinewSemi_Connectivity_Module_Catalogue_EN.pdf)



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